

X2

High-Speed Inline X-ray system

The **X2** is an advanced inline X-ray inspection system designed for high-speed automatic inspection in production lines. Transmission X-ray technology is combined with patented Slice-Filter-Technology (SFT) for double-sided PCB assembly and component inspection. It features fully automated inspection based on a CAD compiled inspection list and uses an inspection model library for the test-strategy definition. The motion system as well as the image acquisition chain meets all demands of high-speed inspection.

MIPS\_Tune is an off-line programming software package including automatic CAD import, CAD com-pile, inspection parameter setting & rule generation. The MIPS\_Verify module included in the MIPS\_Process unit with its closed-loop repair con-cept is capable for in-line or off-line verifcation using a graphical board layout display and X-ray image with defect marking. MIPS-Verify can be linked to combined AOI platforms.

A test coverage display allows optimized inspection concept analyses & balancing. All relevant inspection data can be stored and maintained in a dedicated inspection data base. Our MIPS\_SPC Real Time module is providing real-time process control with immediate production line feedback.

### **Features and Benefits**

- High-speed AXI system Transmission: up to 6 images/s
- Transmission X-ray & Slice Filter Technology<sup>™</sup>
- Inline board handling with automated width adjust
- Microfocus x-ray tube (sealed)
- Dual 3/2 inch image intensifer
- 1k x 1k digital camera with programmable exposure
- 3 axes programmable motion system with variable feld of view
- Automated grey-level and geometrical calibration
- Barcode scanner (1D/2D) for serial number and product type selection

# **Inspection & Process Software**

- PC-Station with multi-core processor setup
- Windows 7 or Windows 10 platform
- Advanced algorithm library for solder joint & component inspection
- Slice Filter Technology<sup>™</sup> (SFT) for double-sided boards
- Automatic Tree Classification (ATC) for auto-rulegeneration
- Off-line programming with auto program generation

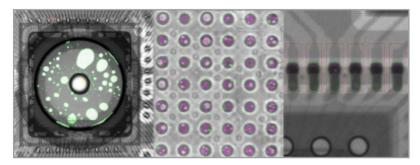


# **Applications**

## **ELECTRONIC COMPONENTS AND SOLDER-JOINT**

A unique advanced algorithm library is available for electronic applications, specifically for component and solder-joint inspection on PCB, hybrid or chip level assembly processes.

- All standard SMD components
- Specifc BGA and QFN algorithm
- Cooling plates/heatsink void inspection



# **Specifications**

### **Facilities**

### **Dimensions:**

1550 mm (H) x 1800 mm (W) x 1600 mm (D)

Adjustable conveyor height:

(SMEMA): 950 mm **Weight:** 3.500 kg

**Safe Operating Temperature:** 

15° - 32 °C

Power Consumption: max. 6 kW

Line Voltage: 400 VAC, 50/60 Hz 3 phase, 16 A

208 VAC, 50/60 Hz 3 phase, 25 A Air: 5-7 Bar, < 2 l/min, filtered (30 $\mu$ ), dry, oil free

# Part Handling / Motion

High-speed sample table with linear drives (X,Y)

Driving distance x,y:  $510 \times 410 \text{ mm}$ Position repeatability:  $\pm -5 \mu \text{m}$ 

Z drive: x-ray tube

Z movement with continous magnification (FoV)

change

X-ray Source (sealed tube)
Energy: 130 kV/40 W
Focal Spot Size: 5 microns

X-Ray Tube Orientation: End window tube

# X-ray Imaging

Detector type: 3" / 2" image intensifer

**Camera:** 1k x 1k, 10 bit

Video output: Camera link interface Video display: High resolution 19" TFT

# Inspection features

## Inspection area

Max. board size: 18" (x)  $\times$  14" (y) /

460 mm (x) x 360 mm (y)

Max. inspection area:  $8"(x) \times 14"(y)$  /

460 mm (x) x 360 mm (y)

Max board weight: 5.5 lbs (2,5 kg)

**Board thickness:** 0.03" – 0.2" (0,8-5 mm)

Standard FoV setup

Transmission FoV: 0.4" (10 mm) to 1.2" (30 mm)

Object resolution (@min. FoV): 8-10 µm

Assembly clearance

Top side (incl. board thickness): 30 mm Bottom side (excl. board thickness): 30 mm For more information, speak with your MatriX representative.

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